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Switching Transistor

NPN Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	40	Vdc
Collector - Base Voltage	V _{CBO}	60	Vdc
Emitter – Base Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous	I _C	600	mAdc
Collector Current – Peak	I _{CM}	900	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) @T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

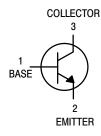
*Transient pulses must not cause the junction temperature to be exceeded.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



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SOT-23 (TO-236) CASE 318 STYLE 6

MARKING DIAGRAM



2X = Specific Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]		
MMBT4401LT1G SMMBT4401LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel		
MMBT4401LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure. BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Cha	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS				•	•	
Collector - Emitter Breakdown Voltage	V _{(BR)CEO}	40	-	Vdc		
Collector - Base Breakdown Voltage	$(I_C = 0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	60	-	Vdc	
Emitter-Base Breakdown Voltage	$(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	6.0	-	Vdc	
Base Cutoff Current	$(V_{CE} = 35 \text{ Vdc}, V_{EB} = 0.4 \text{ Vdc})$	I _{BEV}	-	0.1	μAdc	
Collector Cutoff Current	(V _{CE} = 35 Vdc, V _{EB} = 0.4 Vdc)	I _{CEX}	-	0.1	μAdc	
ON CHARACTERISTICS (Note 3)			•	•		
DC Current Gain		h _{FE}	20 40 80 100 40	- - - 300 -	-	
Collector - Emitter Saturation Voltage	$(I_C = 150 \text{ mAdc}, I_B = 15 \text{ mAdc})$ $(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	V _{CE(sat)}	_ _	0.4 0.75	Vdc	
Base – Emitter Saturation Voltage	V _{BE(sat)}	0.75 -	0.95 1.2	Vdc		
SMALL-SIGNAL CHARACTERISTIC	es .		•	•		
Current-Gain - Bandwidth Product	(I _C = 20 mAdc, V _{CE} = 10 Vdc, f = 100 MHz)	f _T	250	-	MHz	
Collector-Base Capacitance	$(V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	C _{cb}	-	6.5	pF	
Emitter-Base Capacitance	$(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	C _{eb}	-	30	pF	
Input Impedance	mpedance $(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$		1.0	15	kΩ	
Voltage Feedback Ratio	atio $(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$		0.1	8.0	X 10 ⁻⁴	
Small-Signal Current Gain	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h _{fe}	40	500	_	
Output Admittance	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h _{oe}	1.0	30	μmhos	
SWITCHING CHARACTERISTICS			-			
Delay Time	(V _{CC} = 30 Vdc, V _{EB} = 2.0 Vdc,	t _d	-	15	ne	
Rise Time	I _C = 150 mAdc, I _{B1} = 15 mAdc)	t _r	-	20	ns	
Storage Time	$(V_{CC} = 30 \text{ Vdc}, I_{C} = 150 \text{ mAdc},$	t _s	-	225	ne	
Fall Time	$I_{B1} = I_{B2} = 15 \text{ mAdc}$	t _f	-	30	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

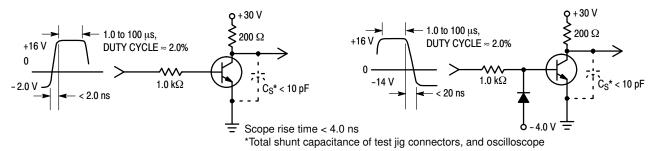


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

TRANSIENT CHARACTERISTICS

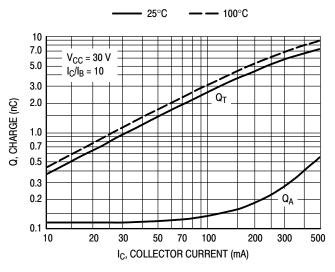


Figure 3. Charge Data

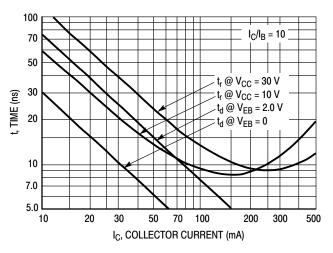


Figure 4. Turn-On Time

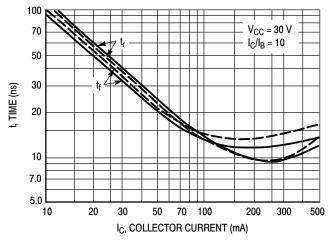


Figure 5. Rise and Fall Times

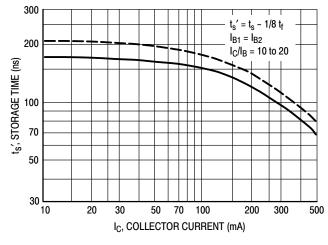


Figure 6. Storage Time

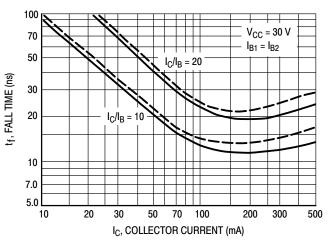


Figure 7. Fall Time

SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE} = 10 \text{ Vdc}$, $T_A = 25^{\circ}\text{C}$; Bandwidth = 1.0 Hz

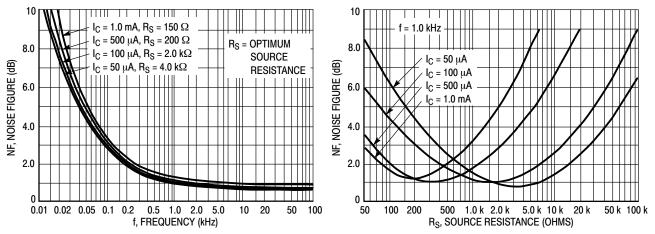


Figure 8. Frequency Effects

Figure 9. Source Resistance Effects

h PARAMETERS

$$V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C}$$

This group of graphs illustrates the relationship between h_{fe} and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were selected from the MMBT4401LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

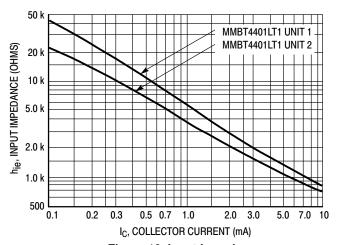


Figure 10. Input Impedance

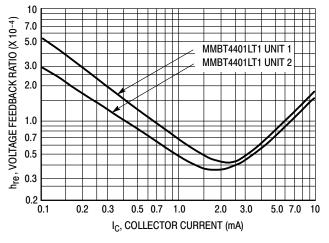


Figure 11. Voltage Feedback Ratio

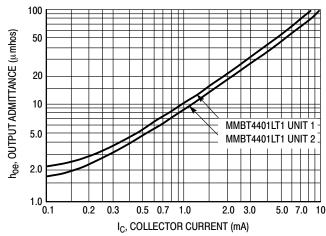


Figure 12. Output Admittance

STATIC CHARACTERISTICS

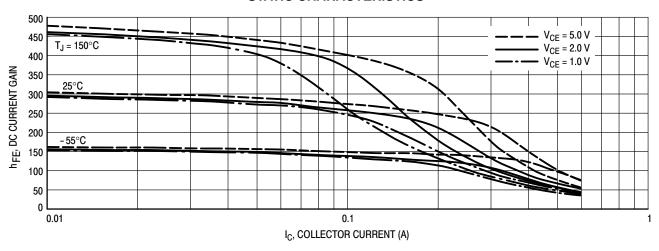


Figure 13. DC Current Gain

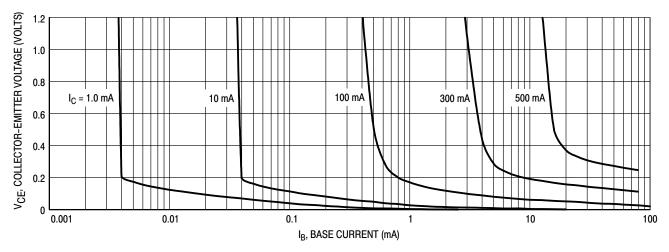


Figure 14. Collector Saturation Region

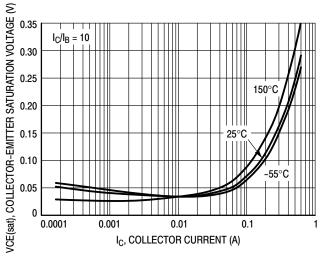


Figure 15. Collector–Emitter Saturation Voltage vs. Collector Current

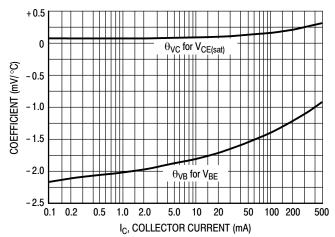


Figure 16. Temperature Coefficients

STATIC CHARACTERISTICS

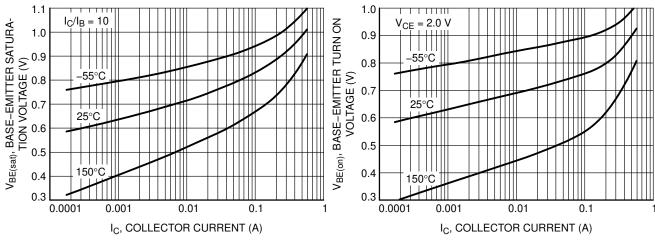


Figure 17. Base-Emitter Saturation Voltage vs. **Collector Current**

Figure 18. Base-Emitter Turn On Voltage vs. **Collector Current**

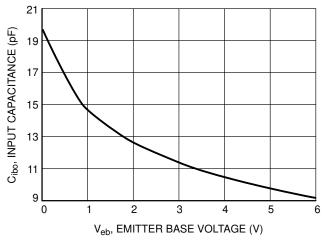


Figure 19. Input Capacitance vs. Emitter Base Voltage

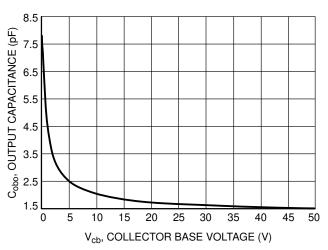


Figure 20. Output Capacitance vs. Collector **Base Voltage**

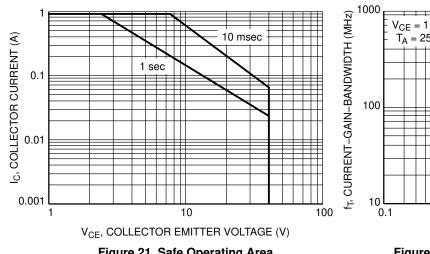


Figure 21. Safe Operating Area

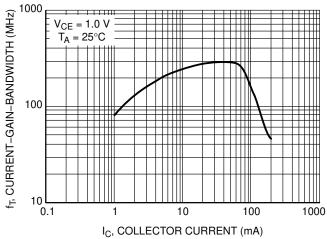
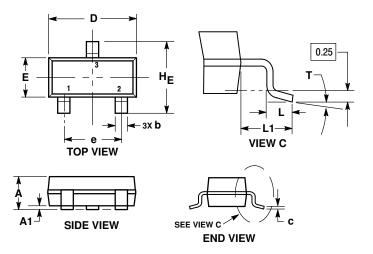


Figure 22. Current-Gain-Bandwidth Product

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AR



NOTES:

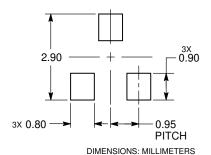
- I. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

STYLE 6:

- PIN 1. BASE
- EMITTER
- 3. COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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